

# BC637

Rev.E Mar.-2016

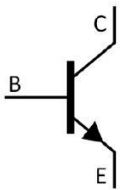
TO-92

NPN

Silicon NPN transistor in a TO-92 Plastic Package.

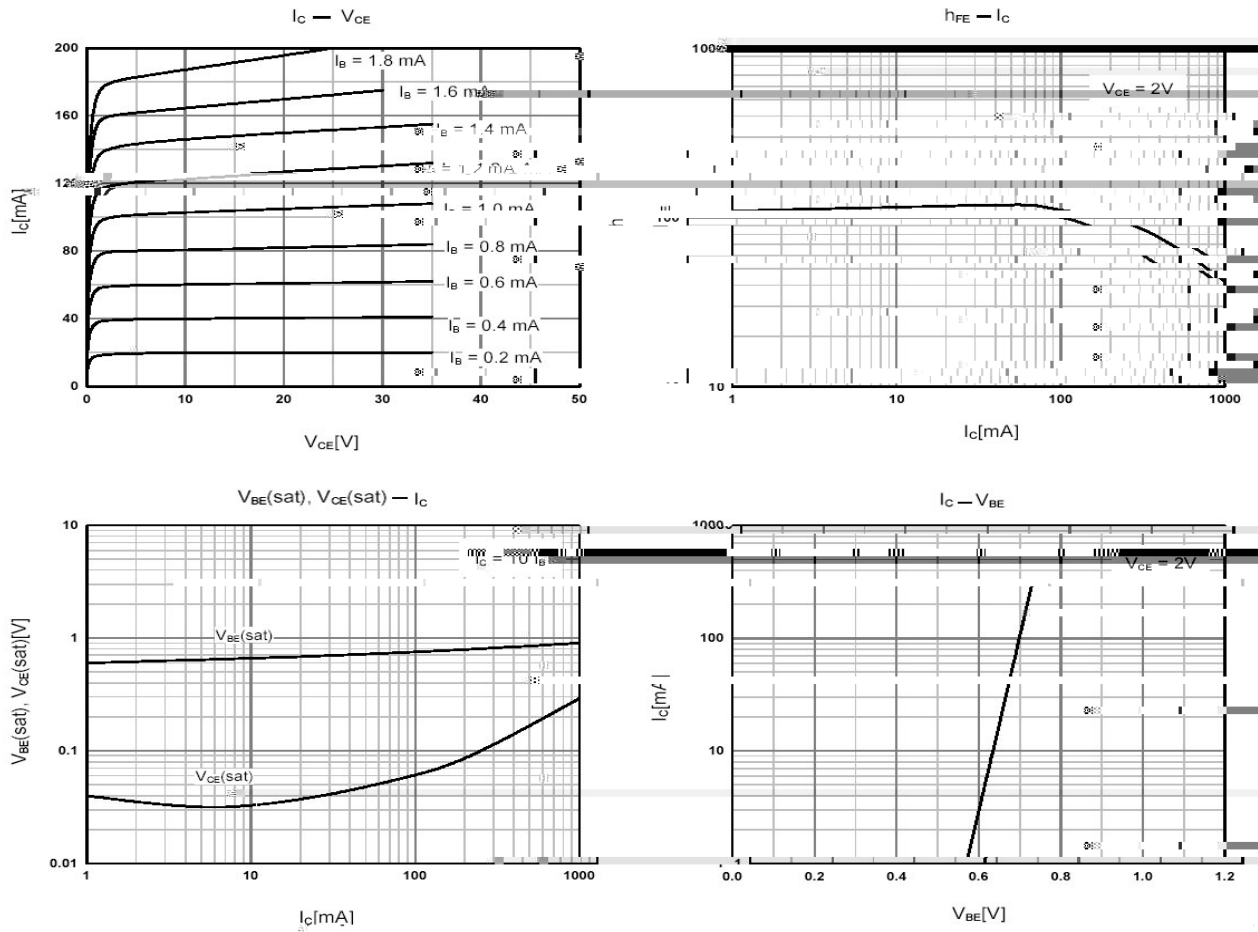
High current, Low voltage.

Driver stages of audio or video amplifiers applications.



| Parameter                      | Symbol    | Rating  | Unit |
|--------------------------------|-----------|---------|------|
| Collector to Base Voltage      | $V_{CBO}$ | 60      | V    |
| Collector to Emitter Voltage   | $V_{CEO}$ | 60      | V    |
| Emitter to Base Voltage        | $V_{EBO}$ | 5.0     | V    |
| Collector Current - Continuous | $I_C$     | 1.0     | A    |
| Peak Collector Current         | $I_{CM}$  | 1.5     | A    |
| Peak Base Current              | $I_{BM}$  | 200     | mA   |
| Total Power Dissipation        | $P_{tot}$ | 830     | mW   |
| Junction Temperature           | $T_j$     | 150     |      |
| Storage Temperature Range      | $T_{stg}$ | -55 150 |      |

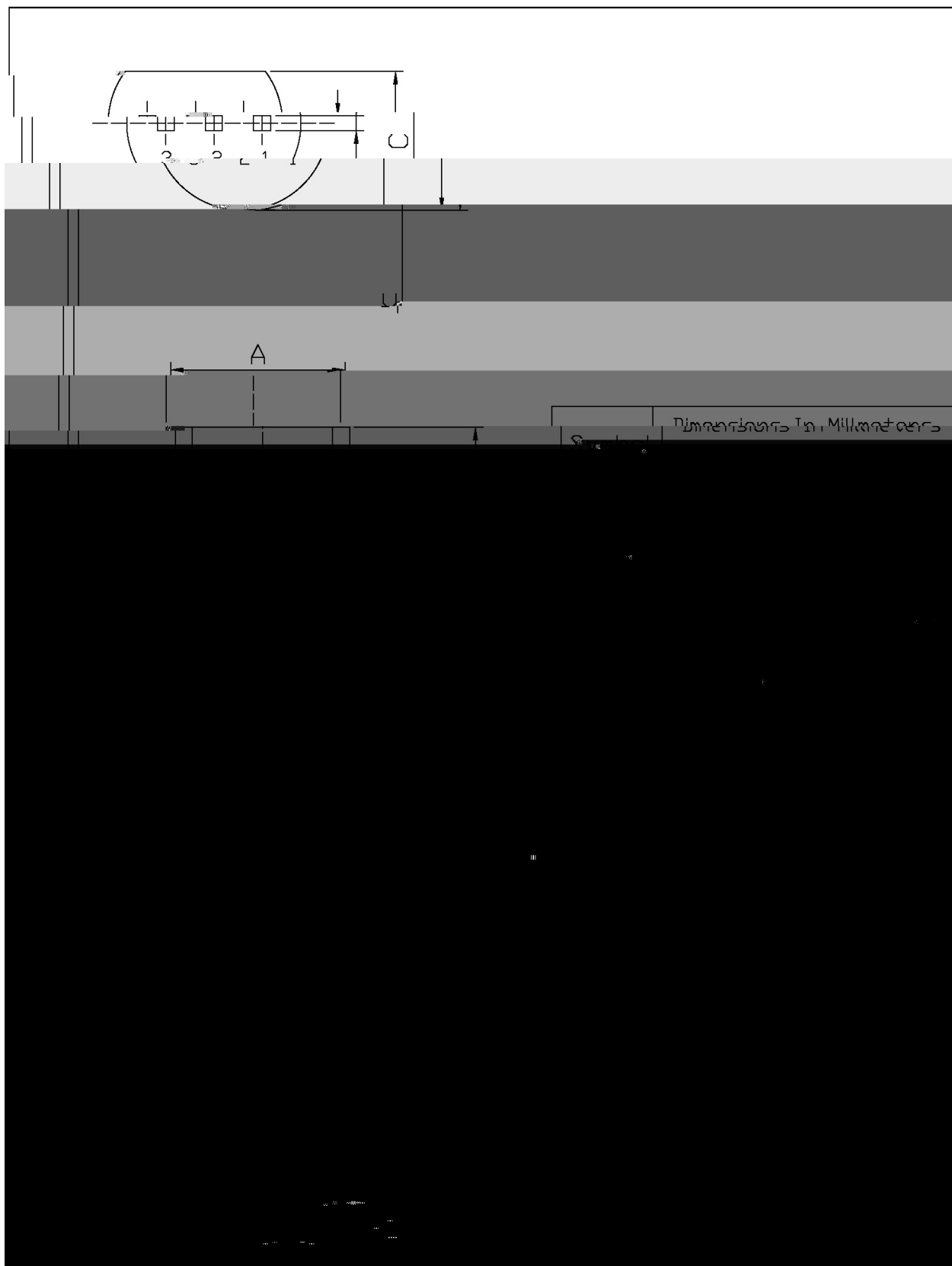
| Parameter                 | Symbol    | Test Conditions      | Min | Typ | Max | Unit    |
|---------------------------|-----------|----------------------|-----|-----|-----|---------|
| Collector Cut-Off Current | $I_{CBO}$ | $V_{CB}=30V$ $I_E=0$ |     |     | 0.1 | $\mu A$ |

**Electrical Characteristic Curve**


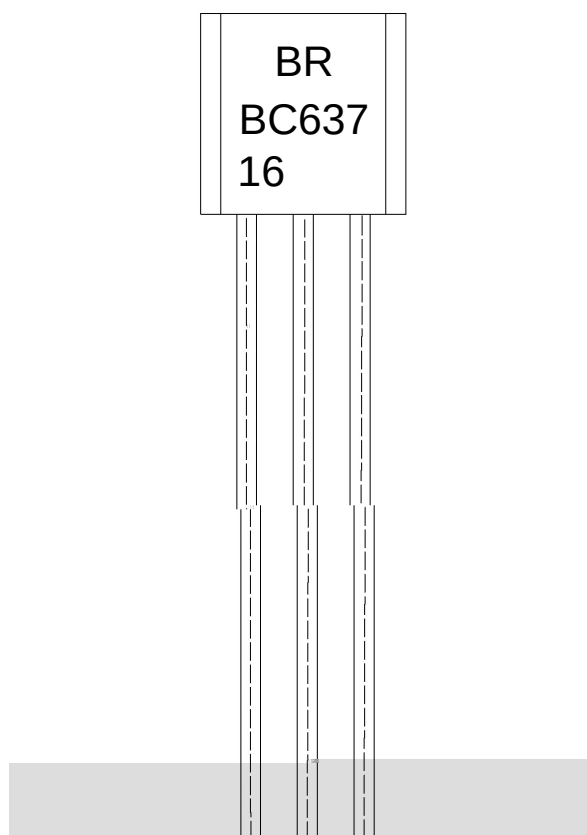
⊂ É Ò Ì f / Package Dimensions

TO-92

Unit: mm



4. 1. 1 / Marking Instructions



BR:

BC637

16:  $h_{FE}$

\*\*\*\*

Note:

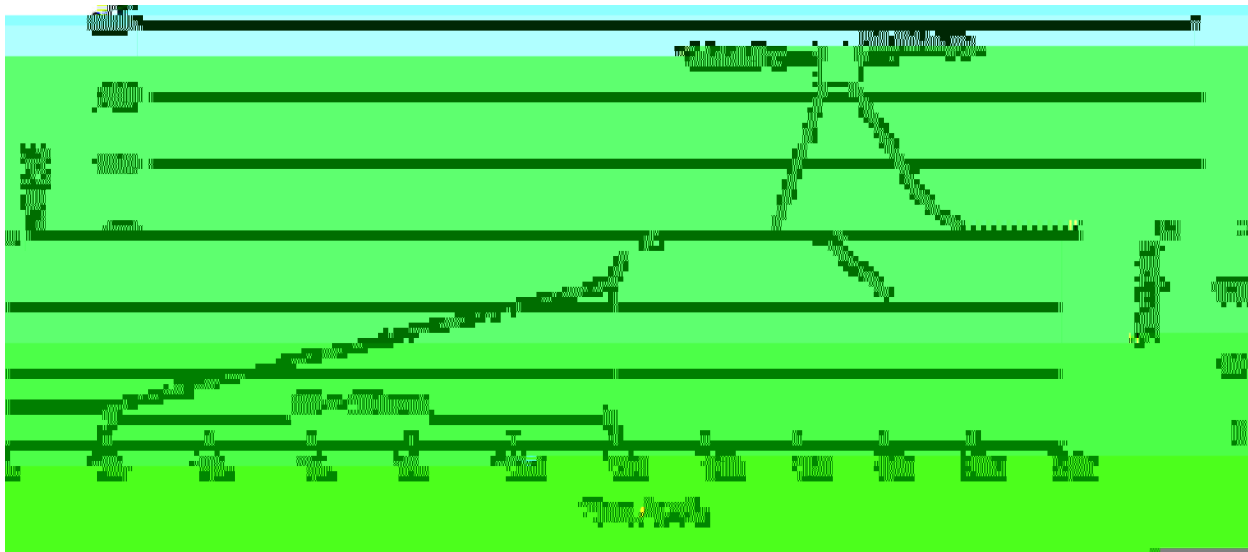
BR: Company Code.

BC637: Product Type.

16:  $h_{FE}$  Classifications Symbol

\*\*\*\*: Lot No. Code, code change with Lot No.

### ↓ \$ ¶ ŵ'E ¶ f (ŵ'ŝ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- |   |       |     |           |                                         |                                      |
|---|-------|-----|-----------|-----------------------------------------|--------------------------------------|
| 1 | 25    | 150 | 60        | 90sec;                                  | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 |     | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |                                      |
| 3 |       | 2   | 10        | /sec.                                   | 3. Cooling Speed: 2~10 /sec.         |

### ↓ ŵ q ŵ'Y ¶ / Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp:270±5

Time:10±1 sec

### ¶ ŵ ŵ'— / Packaging SPEC.

/ BULK

| Package Type<br>封装形式 | Units 包装数量 |    |    |    |    | Dimension 包装尺寸 (unit: mm3) |   |   |
|----------------------|------------|----|----|----|----|----------------------------|---|---|
|                      | 只袋         | 袋盒 | 只盒 | 盒箱 | 只箱 | 袋                          | 盒 | 箱 |
|                      |            |    |    |    |    |                            |   |   |

/ AMMO

| Package Type<br>封装形式 | Units 包装数量 |     |      |    |    | Dimension 包装尺寸 (unit: mm3) |            |
|----------------------|------------|-----|------|----|----|----------------------------|------------|
|                      | 只纸带        | 纸带盒 | 纸带层盒 | 盒箱 | 只箱 | 盒                          | 箱          |
|                      |            |     |      |    |    |                            | 小箱 ,<br>大箱 |

### ä v L'Ŵ / Notices